

HEX BUFFERS WITH OPEN DRAIN OUTPUTS

Description

The 74LVC04A provides six independent inverter buffers. The device is designed for operation with a power supply range of 1.65V to 5.5V. The inputs are tolerant to 5.5V allowing this device to be used in a mixed voltage environment. The device is fully specified for partial power down applications using IOFF. The IOFF circuitry disables the output preventing damaging current backflow when the device is powered down.

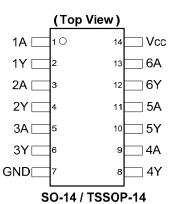
The gates perform the positive Boolean function:

$$Y = \overline{A}$$

Features

- Wide Supply Voltage Range from 1.65V to 5.5V
- Sinks or sources 24mA at V_{CC} = 3.3V
- CMOS low power consumption
- IOFF Supports Partial-Power-Down Mode Operation
- Inputs or outputs accept up to 5.5V
- Inputs can be driven by 3.3 V or 5.5V allowing for voltage translation applications.
- ESD Protection Exceeds JESD 22
 - 200-V Machine Model (A115-A)
 - 2000-V Human Body Model (A114-A)
 - Exceeds 1000-V Charged Device Model (C101C)
- Latch-Up Exceeds 250mA per JESD 78, Class II
- Range of Package Options SO-14 and TSSOP-14
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Pin Assignments



Applications

- Voltage Level Shifting
- General Purpose Logic
- Power Down Signal Isolation
- Wide array of products such as:
 - PCs, networking, notebooks, ultrabooks, netbooks
 - Computer peripherals, hard drives, CD/DVD ROM
 - TV, DVD, DVR, set top box

Notes:

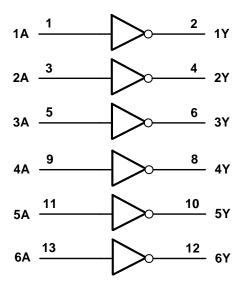
- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.



Pin Descriptions

Pin Number	Pin Name	Description
1	1A	Data Input
2	1Y	Data Output
3	2A	Data Input
4	2Y	Data Output
5	3A	Data Input
6	3Y	Data Output
7	GND	Ground
8	4Y	Data Output
9	4A	Data Input
10	5Y	Data Output
11	5A	Data Input
12	6Y	Data Output
13	6A	Data Input
14	V _{CC}	Supply Voltage

Logic Diagram



Function Table

Inputs	Outputs
Α	Υ
Н	L
L	Н



Absolute Maximum Ratings (Note 4) (@T_A = +25°C, unless otherwise specified.)

Symbol	Description	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	KV
ESD CDM	Charged Device Model ESD Protection	1	KV
ESD MM	Machine Model ESD Protection	200	V
Vcc	Supply Voltage Range	-0.5 to 6.5	V
VI	Input Voltage Range	-0.5 to 6.5	V
Vo	Voltage applied to output in high impedance or I _{OFF} state	-0.5 to 6.5	V
Vo	Voltage applied to output in high or low state	-0.3 to V _{CC} +0.5	V
I _{IK}	Input Clamp Current V _I <0	-50	mA
I _{OK}	Output Clamp Current Vo<0	-50	mA
Io	Continuous output current	50	mA
	Continuous current through Vdd or GND	±100	mA
TJ	Operating Junction Temperature	-40 to +150	°C
T _{STG}	Storage Temperature	-65 to +150	°C
P _{TOT}	Total Power Dissipation	500	mW

Note: 4. Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.

Recommended Operating Conditions (Note 5) (@TA = +25°C, unless otherwise specified.)

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC}	Supply Voltage		1.65	5.5	V
VI	Input Voltage		0	5.5	V
	Output Voltage	Active Mode	0	V_{CC}	V
Vo		V _{CC} = 0V; Power Down Mode	0	5.5	V
A 1 / A > /	Lancet transaction with a second all mater	V _{CC} = 1.65V to 2.7V		20	0.7
Δt/ΔV	Input transition rise or fall rate	V _{CC} = 2.7V to 5.5V		10	ns/V
TA	Operating free-air temperature		-40	+125	°C

Notes: 5. Unused inputs should be held at VCC or Ground.



Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Comple at	Down of	Took Conditions	V	$T_A = -40^{\circ}C$	C to +85°C	$T_A = -40^{\circ}C$	to +125°C	l lmit
Symbol	Parameter	Test Conditions	V _{cc}	Min	Max	Min	Max	Unit
			1.65V to 1.95V	0.65 X V _{CC}		0.65 X V _{CC}		
\ /	High-level Input		2.3V to 2.7V	1.7		1.6		.,
V_{IH}	Voltage		2.7V to 3.6V	2.0		2.0		V
			4.5V to 5.5V	0.7 X V _{CC}		2.0		
			1.65V to 1.95V		0.35 X V _{CC}		0.35 X V _{CC}	
	Low-level input		2.3V to 2.7V		0.7		0.7	.,
V_{IL}	voltage		2.7V to 3.6V		0.8		0.8	V
			4.5V to 5.5V		0.3 X V _{CC}		0.3 X V _{CC}	
		I _{OH} = -100μA	1.65V to 3.6V	V _{CC} - 0.2		V _{CC} - 0.3		
	, High Level	I _{OH} = -4mA	1.65V	1.2				
\		I _{OH} = -8mA	2.3V	1.9				V
V_{OH}	Output Voltage	10 1	2.7V	2.2		2.05		
		I _{OH} = -12mA	3.0V	2.3		2.1		
		I _{OH} = -24mA	3.0V	2.2		2.0		
		I _{OH} = 100μA	1.65V to 5.5V		0.2		0.3	
		I _{OH} = 4mA	1.65V		0.45		0.6	
\	High-level	I _{OH} = 8mA	2.3V		0.70		0.85	.,
V_{OL}	Output Voltage	104	2.7V		0.40		0.6	V
		I _{OH} = 12mA	3.0V		0.55		0.6	
		I _{OH} =-24mA	3.0V		0.55		0.6	
II	Input Current	V _I =GND to 5.5V	3.6V		±5		±20	μA
I _{OFF}	Power Down Leakage Current	V_1 or $V_0 = 0V$ to 3.6V	0		10		20	μА
I _{CC}	Supply Current	$V_I = GND \text{ or } V_{CC}$ $I_O = 0$	3.6V		10		40	μΑ
ΔI _{CC}	Additional Supply Current	One input at V _{CC} – 0.6V Other	2.7V to 3.6V		500		5000	μA



Switching Characteristics

Cumbal	Parameter	Test	V	T,	_A = +25°	C	-40°C to	+85°C	-40°C to	+125°C	Unit
Symbol		Conditions	V _{CC}	Min	Тур	Max	Min	Max	Min	Max	Unit
			1.65V to1.95V	0.5	4.1	7.5	0.5	8.0	0.5	9.5	
	Propagation	Figure 4	2.3V to 2.7V	0.5	3.6	7.0	0.5	7.5	0.5	9.0	
t _{PD}	Delay A _N to Y _N	Figure 1	2.7V	0.5	3.0	5.3	0.5	5.5	0.5	7.0	ns
			3V to 3.6V	0.5	2.5	4.3	0.5	4.5	0.5	6.0	
t _{SK(0)}	Output Skew Time		3V to 3.6V					1.0		1.5	ns

Operating Characteristics (@T_A = +25°C, unless otherwise specified.)

	Parameter	Test	V _{CC} = 1.8V	V _{CC} = 2.5V	$V_{CC} = 3.3V$	V _{CC} = 5V	Unit
	Parameter	Conditions	Тур	Тур	Тур	Тур	Onit
C _{pd}	Power dissipation capacitance per gate	f = 10 MHz	7.0	7.5	8.0	8.6	pF
Cı	Input Capacitance	$V_i = V_{CC} - or$ GND	4	4	4	4	pF

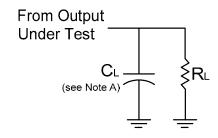
Package Characteristics

Symbol	Parameter	Test Conditions	V _{cc}	Min	Тур	Max	Unit
0	Thermal Resistance	SO-14	(Note 6)		TBD		°C/W
θ _{JA}	Junction-to-Ambient TSSOP-14		(Note 6)		159		C/VV
0	Thermal Resistance	SO-14	(Note 6)		TBD		°C/W
θ _{JC}	Junction-to-Case	TSSOP-14	(Note 6)		25		C/VV

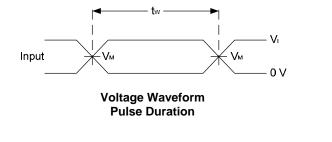
Note: 6. Test condition for SO-14 and TSSOP-14: Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

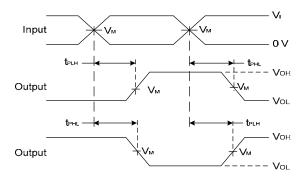


Parameter Measuement Information



V	Inj	outs	V	C	D.	
V _{CC}	VI	t _r /t _f	V _M	C∟	RL	
1.8V ±0.15V	V _{CC}	≤2ns	V _{CC} /2	30pF	1ΚΩ	
2.5V ±0.2V	V _{CC}	≤2ns	V _{CC} /2	30pF	500Ω	
3.3V ±0.3V	3V	≤2.5ns	1.5V	50pF	500Ω	
5V ±0.5V	Vcc	≤2.5ns	V _{CC} /2	50pF	500Ω	





Voltage Waveform Propagation Delay Times Inverting and Non Inverting Outputs

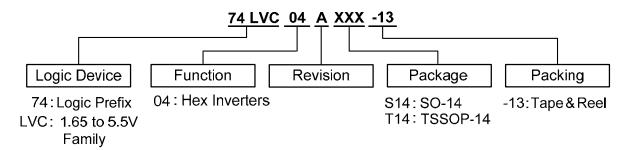
Notes: A. Includes test lead and test apparatus capacitance.

- B. All pulses are supplied at pulse repetition rate ≤ 10 MHz.
 C. Inputs are measured separately one transition per measurement.
- D. t_{PLH} and t_{PHL} are the same as t_{PD}.

Figure 1. Load Circuit and Voltage Waveforms



Ordering Information

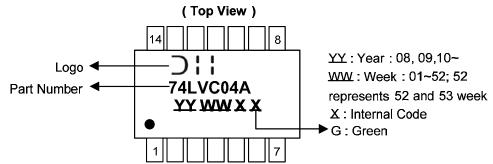


	Device	Package	Packaging	13" Tape and Reel	
		Code	(Note 7)	Quantity	Part Number Suffix
Pb	74LVC04AS14-13	S14	SO-14	2500/Tape & Reel	-13
Pb	74LVC04AT14-13	T14	TSSOP-14	2500/Tape & Reel	-13

Notes: 7. The taping orientation and tape details can be found at http://www.diodes.com/datasheets/ap02007.pdf

Marking Information

(1) SO-14, TSSOP-14

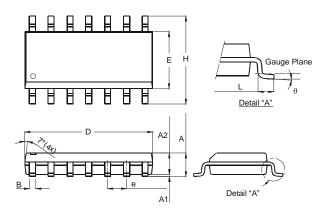


Part Number	Package
74LVC04AS14	SO-14
74LVC04AT14	TSSOP-14



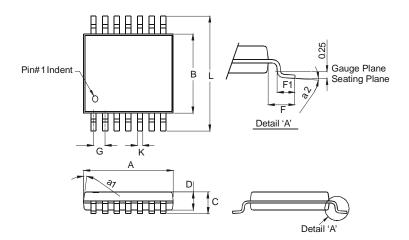
Package Outline Dimensions (All dimensions in mm.)

Package Type: SO-14



	SO-14			
Dim	Min	Max		
Α	1.47	1.73		
A1	0.10	0.25		
A2	1.45 Typ			
В	0.33	0.51		
D	8.53	8.74		
Е	3.80	3.99		
е	1.27	Тур		
Н	5.80	6.20		
L	0.38	1.27		
θ	0°	8°		
All Di	mensions	s in mm		

Package Type: TSSOP-14

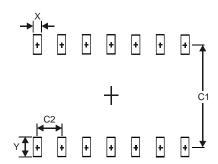


TSSOP-14		
Dim	Min	Max
a1	7° (4X)	
a2	0°	8°
Α	4.9	5.10
В	4.30	4.50
С	_	1.2
D	0.8	1.05
F	1.00 Typ	
F1	0.45	0.75
G	0.65 Typ	
K	0.19	0.30
L	6.40 Typ	
All Dimensions in mm		



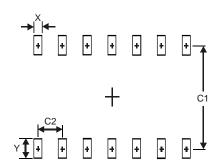
Suggested Pad Layout

Package Type: SO-14



Dimensions	Value (in mm)	
Х	0.60	
Y	1.50	
C1	5.4	
C2	1.27	

Package Type: TSSOP-14



Dimensions	Value (in mm)	
Х	0.45	
Y	1.45	
C1	5.9	
C2	0.65	



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